



DEC 29 2004

**TRANSMITTAL LETTER**  
**(General - Patent Pending)**Docket No.  
P0338DIV

In Re Application Of: Chun-Cheng Tsao and John Valliant

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/693,310	10/24/2003	Shantese McDonald		3723	1505

Title: Method and Apparatus for Global Die Thinning and Polishing of Flip-Chip Packaged Integrated Circuits

COMMISSIONER FOR PATENTS:

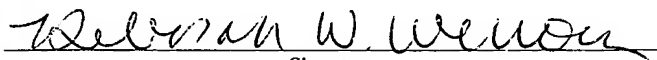
Transmitted herewith is:

Amendment Transmittal Letter  
Amendment and Response to Office Action (15 pp)  
Return Receipt Postcard

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 19-0603 as described below.
- ☐ Charge the amount of \_\_\_\_\_
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.
- ☐ Payment by credit card. Form PTO-2038 is attached.

**WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.**

  
Signature

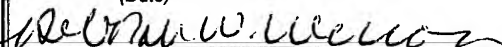
Dated: December 23, 2004

Deborah W. Wenocur, Reg. No. 40,221  
Agent for Applicant  
c/o Shelly Garrett  
Credence Systems Corp.  
1421 California Circle  
Milpitas, CA 95035

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

December 24, 2004

(Date)



Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

cc:

**BEST AVAILABLE COPY**

**AMENDMENT TRANSMITTAL LETTER (Large Entity)**

Applicant(s): Chun-Cheng Tsao and John Valliant

Docket No.

P0338DIV

Application No.

10/693,310

Filing Date

10/24/2003

Examiner

Shantese McDonald

Customer No.

Group Art Unit

3723

Confirmation No.

1505

Invention:  Method and Apparatus for Global Die Thinning and Polishing of Flip-Chip Packaged IntegratedCOMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

## CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	28 -	29 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	8 -	8 =	0	x \$86.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_
- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 19-0603
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.
- ☐ Payment by credit card. Form PTO-2038.

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Signature

Dated: December 23, 2004

Deborah W. Wenocur, Reg. No. 40,221  
Agent for Applicant  
c/o Shelly Garrett  
Credence Systems Corp.  
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December 24, 2004

(Date)

  
Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

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FFW

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William W. W. W.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: Chung-Chen Tsao and John Valliant ) Grp Art Unit: 3723  
Assignee: Credence Systems Corporation ) Ex: Shantese McDonald  
Serial Number: 10/693,310  
Filed: October 24, 2003  
For: METHOD AND APPARATUS FOR  
BACKSIDE DIE THINNING AND  
POLISHING OF PACKAGED  
INTEGRATED CIRCUITS

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir,

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

This is in response to the Office Action dated December 1, 2004.

Please amend the instant application as follows: